Getting started with Bluetooth® low energy
CC2541, CC2541-Q1, CC2540, & CC2540T for IAR users
Proven and robust, Bluetooth® 4.0 compliant

Order
Development kit for catalog, high temperature, and automotive devices featuring CC2540 USB dongle, CC2541 keyfob, and debugger.

Demo
Run the preprogrammed Bluetooth® low energy keyfob demo.

Develop
Leverage sample applications in the SDK.

Enhance
More advanced examples outside of the SDK.

Support
Other resources to aid development.
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